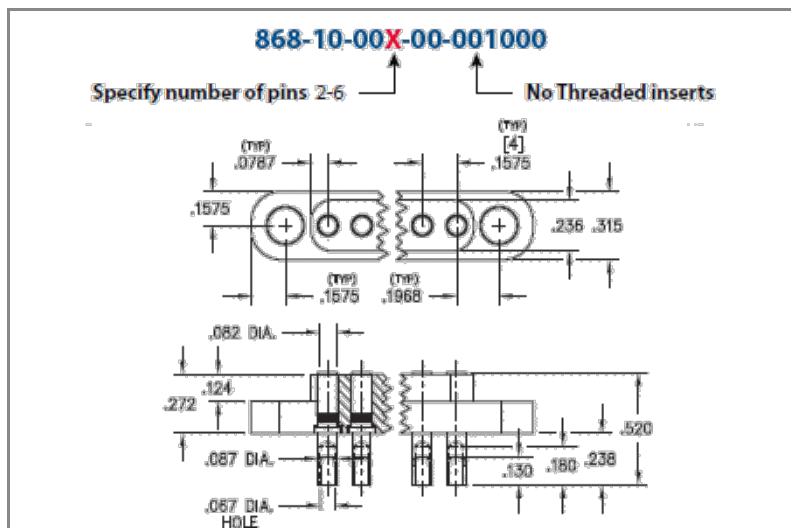


**PRODUCT NUMBER: 868-10-006-00-001000**



**DESCRIPTION**

Interconnect Flat Face Spring-Loaded Target Connector  
 Spring-Loaded Target Connector  
 Rugged, Vertical Mount Soldercup Target; Flat Face  
**Rows:** Single Row (1)  
**Pitch:** .158" (4,001mm)  
**Clip Grid:** 00  
**Pin Window Pattern** 001  
**Plating Code:** 10  
     **Shell:** 10 μ" Gold over 100 μ" Nickel  
**Insulator Pin Clip Type:** 000  
**Packaging:** Packaged in Tubes  
**Insulator Information:**  
 Nylon 46 High Temperature

# Pins	Qty Tube	ROHS Compliant
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**LOOSE PIN/RECEPTACLE USED:**

1968 (Brass Alloy)

**BRASS ALLOY 360 per ASTM B 16, or 385 per ASTM B455**

**Properties of BRASS ALLOY 360 ASTM B 16:**

- Chemical composition: Cu 63% (max), Pb 3.7% (max)†, Fe .35% (max), Zn remainder
- Temper as machined: H02/H04
- Yield Strength: 25-45 ksi
- Tensile strength: 57-80 ksi
- Hardness as machined: 80-90 Rockwell B
- Electrical conductivity: 26% IACS\*
- Melting point: 1000 °C/840 °C (liquidus/solidus)

**Properties of BRASS ALLOY 385 ASTM B 455:**

- Chemical composition: Cu 60% (max), Pb 3.5% (max)†, Fe .35% (max), Zn remainder
- Temper as machined: H02/H04
- Yield Strength: 16 ksi(min)
- Tensile strength: 48 ksi(min)
- Hardness as machined: 80-90 Rockwell B
- Electrical conductivity: 28% IACS\*
- Melting point: 1000 °C/840 °C (liquidus/solidus)

After machining, brass parts are often annealed (softened) for subsequent bending, swaging or crimping. A partial anneal down to  $60 \pm 10$  RB is recommended for  $90^\circ$  bends, a full anneal down to  $35 \pm 15$  RB is recommended for pins or terminals that are swaged (riveted) to a circuit board or crimped to a wire.

**Note:** Plated Brass parts need a barrier plate to prevent zinc diffusion,  $50 \mu\text{m}$  min. nickel or  $100 \mu\text{m}$  min. copper is recommended by ASTM B 545 and 579. ASTM B 488 also recommends a  $50 \mu\text{m}$  min. nickel barrier plate beneath gold to prevent copper diffusion inherent with all copper alloy products.

†RoHS-2 directive 2011/65/EU, exemption 6c allows up to 4% lead as an alloy agent in copper.

\*International Annealed Copper Standard, i.e. as a % of pure copper.

## INSULATOR MATERIAL:

### Nylon 46 (Injection Molded)

Properties:


- High Temp. {30% glass filled} or {45% glass filled}, (black). Flammability rating UL 94 V-0
- Material Heat Deflection Temp. (per ASTM D 648):  $554^\circ\text{F}$  ( $290^\circ\text{C}$ ) @ 264 psi

Note: Materials with HDT above  $446^\circ\text{F}$  ( $230^\circ\text{C}$ ) are considered suitable for "eutectic" reflow soldering. For "lead-free" reflow soldering, choose materials with an HDT above  $500^\circ\text{F}$  ( $260^\circ\text{C}$ ).

## ADDITIONAL NOTES & SPECIFICATIONS

In the interest of improved design, quality and performance, Mill-Max reserves the right to make changes in its specifications without prior notice. Specifications and tolerances are provided wherever possible. Due to the wide variety of interconnects Mill-Max offers, the specific tolerances vary from product to product. If you need information regarding the tolerance of a particular part, please contact Technical Services.

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